

5x5 Via-Array on 10 Cavity PCB

Morten Schierholz {morten.schierholz@tuhh.de}

Institut für Theoretische Elektrotechnik, Hamburg University of Technology (TUHH), Hamburg, Germany

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I. DESCRIPTION

The 5×5 via array is located on a 10 cavity printed circuit board (PCB), as shown in Fig 2. The connectivity of GND and signal vias is shown in Fig 2 (a), with a via ratio of 2 : 1 for signal and GND, respectively. At each via two ports are placed one at the top (odd numbers) of the PCB and one at the bottom (even numbers) . A more thoroughly description is given in [1]. This array is used for a high density IC package. All planes of the stackup are connected by GND vias. The radius of the via barrel is smaller than the radius of the via pads on top and bottom of the stackup, as shown in Fig. 2 (a). All pad of the signal vias are exactly as the via radius ($pad_radius-2.5$ mil). For the top most and bottom most plane (GND planes) the pad radius is pad_radius .

II. MODELING TOOL

All simulations have been carried out with a physics-based (PB) approach [2]–[4]. ~~A demo version of the tool can be accessed over www.tet.tuhh.de.~~ All information regarding the setup are described in the following.

III. PARAMETER

If a value is given in the tables the parameter is not altered during the simulations. On the other hand if the value is varied the according entry of the $\langle parameter.csv \rangle$ file is given.

A. Via Model

The dimensions of the vias used in the structure shown in Fig. 2 are given in Fig. 1. All vias are based on this model. For the dielectric material (Dielectric) the rel. permittivity (ϵ_r) and the loss tangent ($\tan \delta$) are given. For the conductive material (Metal) the conductivity (σ) is given. An overview is given in Tab. I.

Table I: Overview of the parameters used in the via model, as shown in Fig. 1

Parameter	Value
via radius	$pad_radius-2.5$ mil
antipad radius	$antipad_radius$
pad radius plane	pad_radius
pad radius signal	$pad_radius-2.5$ mil

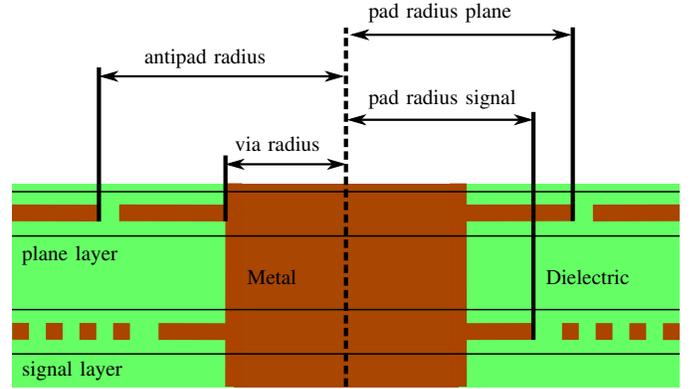


Fig. 1: Via model used for all vias of the structure. If the radius values are not given the via_radius is used for pad_radius_plane , and pad_radius_signal .

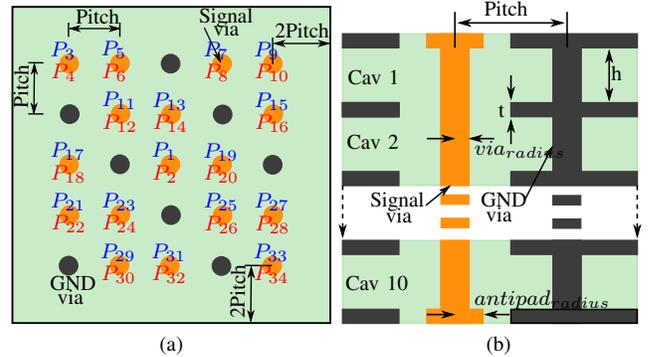


Fig. 2: (a) is the top view in the 5×5 via-array, (b) is the stackup. GND vias are connected to all ground planes. The ports are placed on top and bottom of the PCB. Top ports are blue (odd numbers), bottom ports are red (even numbers).

B. Materials

Two different materials were used, the material for the metal e.g. planes, striplines, vias, pads, and the material for the dielectric e.g. cavity filling, antipad. The metal requires two parameter conductivity (σ) and rel. permeability (μ_r). The dielectric has the rel. permittivity (ϵ_r) and the loss tangent ($\tan \delta$). An overview is given in Tab. II.

C. Stackup

For the stackup general parameters are introduced. If not stated differently in the description the naming refers to all cavities of the stackup. One cavity is defined by the enclosed dielectric material by two planes, as shown in Fig. 3. Signal

Table II: Overview of the material parameters used in the structure.

Parameter	Value
σ	1×10^{30} S/m
μ_r	1
ϵ_r	epsilon_r
$\tan \delta$	loss_tangent

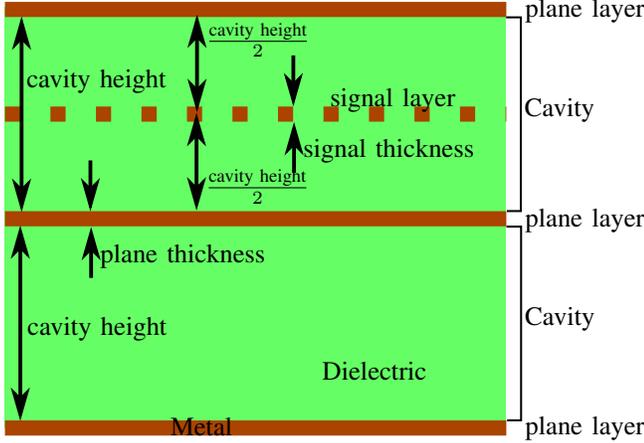


Fig. 3: Stackup nomenclature for the problem. The naming refers to all cavities unless stated differently in the description.

layers are defined in the middle of the cavity. The cavity height is the distance between two plane layers (here diel_height).

Table III: Overview of the parameters related to the stackup used in the PCB.

Parameter	Value
cavity height	diel_height
plane thickness	plane_thickness
signal thickness	plane_thickness

D. File <parameter.csv>

The file <parameter.csv> has all necessary information for the setup of the geometry and parameter variations. The columns are:

- index
- simuIndex
- antipad_radius
- pad_radius
- via_pitch
- diel_height (h)
- plane_thickness
- epsilon_r
- loss_tangent

Index is the row in the <parameter.csv>, diel_height is the distance between the two metal planes, epsilon_r is the relative permittivity (ϵ_r) of the dielectric between the power and ground planes, loss_tangent is $\tan(\delta)$ of the dielectric, plane_thickness is thickness of plane layers, via_pitch is the distance between vias in the array, pad_radius is the radius of

the via pad on top and bottom of the PCB, antipad_radius is the radius of the cutout around a via, simuIndex is the simulation index (<index>) to find the simulation results.

IV. PUBLICATIONS

This structure was used in [1].

REFERENCES

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- [2] R. Rimolo-Donadio, X. Gu, Y. Kwark, M. Ritter, B. Archambeault, F. de Paulis, Y. Zhang, J. Fan, H.-D. Brüns, and C. Schuster, "Physics-Based Via and Trace Models for Efficient Link Simulation on Multilayer Structures Up to 40 GHz," *IEEE Transactions Microwave Theory and Techniques*, vol. 57, no. 8, pp. 2072–2083, Aug. 2009.
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